



Wideband 5G Ceramic SMD Antenna

Part No: PA.176.A

Description:

High-Band 5G Ceramic SMD Antenna covering 1.7-6GHz

Features:

Patent Pending Ceramic Antenna Covering 1.7 - 6GHz High Efficiency across all cellular High-Bands Small Footprint Dimensions: 20 x 10 x 3mm Surface Mount Distribution (SMD) - Supplied on Tape & Reel Manufactured in our IATF16949 Certified Facility





1.	Introduction	3
2.	Specifications	4
3.	Antenna Characteristics	6
4.	Radiation Patterns	8
5.	Mechanical Drawing	10
6.	Integration Guide	11
7.	Solder Reflow Profile	19
8.	Packaging	20
	Changelog	21

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Introduction

1.



The PA.176.A is a patent-pending, 5G/4G high-band cellular SMD antenna designed especially for direct mount on a device's PCB. It provides very high efficiency across multiple cellular bands, operating between 1.7 - 6GHz, in an extremely small form factor. The shape and compact size of just 20*10*3mm, allows the PA.176.A to be easily integrated solution for mounting on the edge of the device's PCB. It is lightweight and is the perfect antenna for mounting on a PCB where space may be limited, as the keep out area for other electronic components, is minimal. Using SMD (on-board) antennas saves on assembly, cable, and connector costs. SMD antennas also lead to higher integration yield rates, higher transmit power and higher sensitivity.

Typical cellular applications include:

- Telematic Control and On-board Diagnostic Units
- Wireless Medical Devices
- First Responder and Public Safety Devices
- UAV's and Robotics
- Media and Smart Home

Care should be taken to the follow layout instructions provided in Section 6 of this datasheet and in placing antenna on the edge of board with adequate clearance to metal. Minimum ground-plane requirements must be met to achieve targeted efficiencies. The PA.176.A is manufactured in Taoglas' IATF16949 Certified Facility and is suitable for automotive applications.

Taoglas provides optimization services for matching, and active TRP, TIS and RSE testing. Integration files for the PA.176.A can be downloaded from the **product page** on the website. For further information or additional support please contact your regional Taoglas customer support team.



2. Specifications

Electrical										
Band	Frequency (MHz)	Efficiency (%)	Average Gain (dB)	Peak Gain (dBi)	VSWR	Impedance	Polarization	Radiation Pattern		
4G/3G Band 3,4,9,25,35,66	1710~1880	77	-1.5	3						
4G/3G Band 1,2,3,9,25,35,39	1850~1990	72	-1.6	3.3						
4G/3G Band 1,2,4,23,25	1920~2170	72	-1.4	3.8						
4G/3G Band 7,30,38,40,41	2300~2690	65	-1.6	4.5	<3:1	<3:1 50 Ω	50 Ω Linear	50 Ω Linear Om	Linear Omni	Omni
5G/4G Band 22,42,78	3300~3500	55	-2.5	3.7						
5G/4G Band 22,42,43,48,77,78,79	3200~4650	58	-2.4	3.6						
Greater than 5GHz	5150~5925	64	-2	2.8						

*Results on 60mm EVB

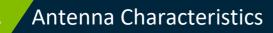
Mechanical			
Dimension 20*10*3 mm			
Material Ceramic			
Termination	Ag (environmental Pb free) - Solder Pad		
EVB Connector	SMA-Female		
Weight	1.8g		
Environmental			
Temperature Range	-40°C to 85°C		
Moisture Sensitivity	Level 3		



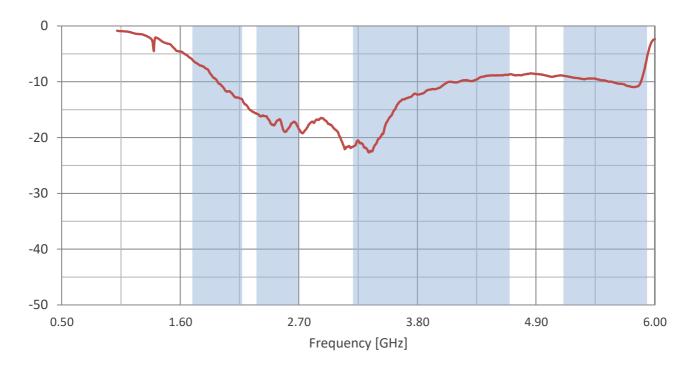
5G/4G Bands				
Band Number	5GNR / FR1 / LTE / LTE-Advanced / WCDMA / HSPA / HSPA+ / TD-SCDMA			
	Uplink	Downlink	Covered	
1	UL: 1920 to 1980	DL: 2110 to 2170	\checkmark	
2	UL: 1850 to 1910	DL: 1930 to 1990	\checkmark	
3	UL: 1710 to 1785	DL: 1805 to 1880	\checkmark	
4	UL: 1710 to 1755	DL: 2110 to 2155	\checkmark	
5	UL: 824 to 849	DL: 869 to 894	3	
7	UL: 2500 to 2570	DL:2620 to 2690	\checkmark	
8	UL: 880 to 915	DL: 925 to 960	*	
9	UL: 1749.9 to 1784.9	DL: 1844.9 to 1879.9	\checkmark	
11	UL: 1427.9 to 1447.9	DL: 1475.9 to 1495.9	\checkmark	
12	UL: 699 to 716	DL: 729 to 746	*	
13	UL: 777 to 787	DL: 746 to 756	*	
14	UL: 788 to 798	DL: 758 to 768	*	
17	UL: 704 to 716	DL: 734 to 746	*	
18	UL: 815 to 830	DL: 860 to 875	*	
19	UL: 830 to 845	DL: 875 to 890	*	
20	UL: 832 to 862	DL: 791 to 821	*	
21	UL: 1447.9 to 1462.9	DL: 1495.9 to 1510.9	\checkmark	
22	UL: 3410 to 3490	DL: 3510 to 3590	\checkmark	
23	UL:2000 to 2020	DL: 2180 to 2200	\checkmark	
24	UL:1625.5 to 1660.5	DL: 1525 to 1559	\checkmark	
25	UL: 1850 to 1915	DL: 1930 to 1995	\checkmark	
26	UL: 814 to 849	DL: 859 to 894	*	
27	UL: 807 to 824	DL: 852 to 869	*	
28	UL: 703 to 748	DL: 758 to 803	*	
29	UL: -	DL: 717 to 728	*	
30	UL: 2305 to 2315	DL: 2350 to 2360	\checkmark	
31	UL: 452.5 to 457.5	DL: 462.5 to 467.5	*	
32	UL: -	DL: 1452 - 1496	√	
35	1850	to 1910	1	
38	2570	to 2620	√	
39	1880	to 1920	1	
40		to 2400	1	
41		to 2690	1	
42		to 3600	1	
43		to 3800	√	
48		to 3700	1	
66	UL: 1710-1780	DL: 2110-2200	√	
71		to 698	*	
74/75/76		to 1518	*	
77		to 4200	1	
78		to 3800	1	
79		to 5000	✓ ₩	
126	410	to 430	×	

*Covered bands represent those with greater than 20% efficiency

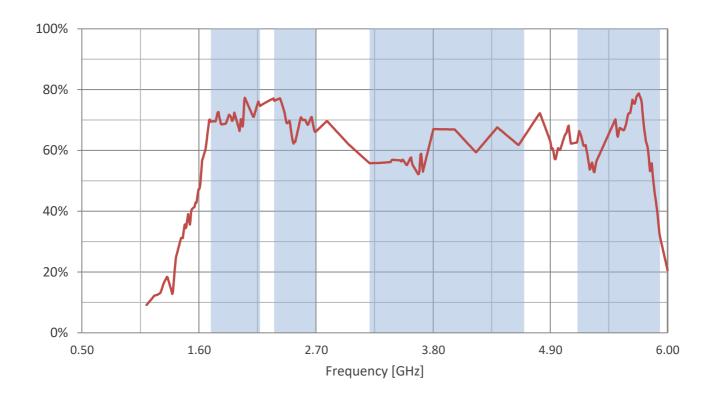




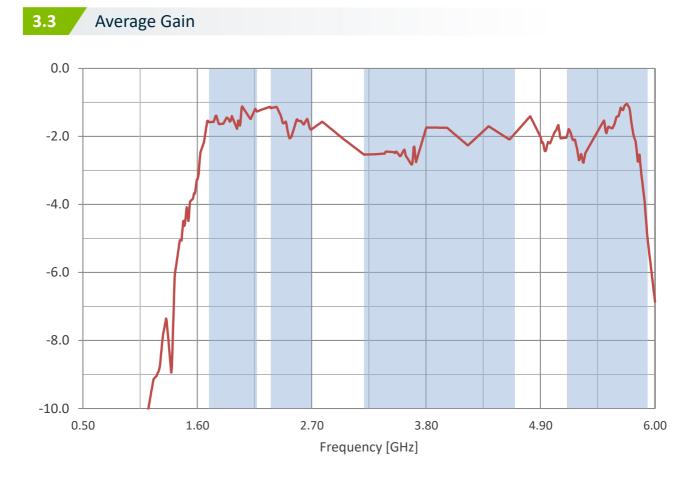


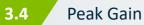


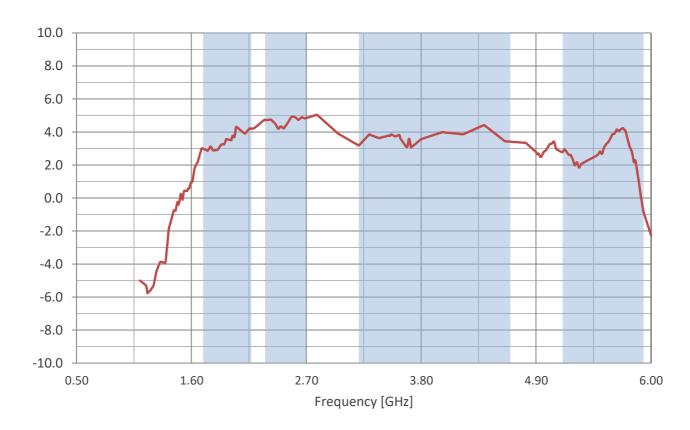
3.2 Efficiency











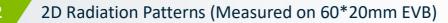


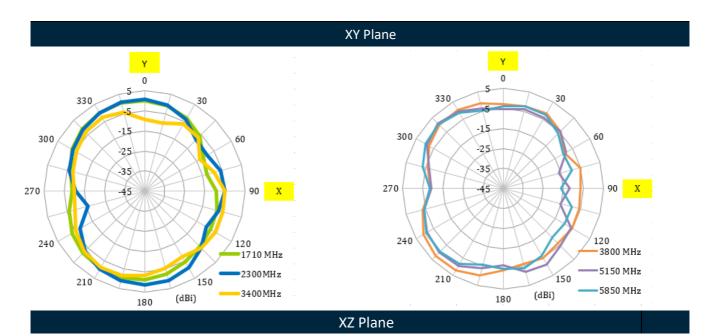


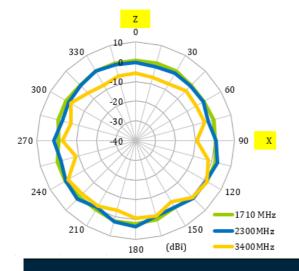


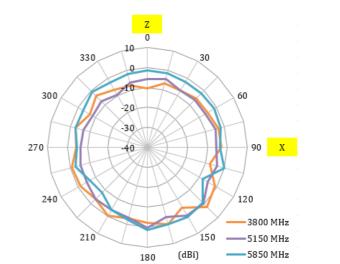




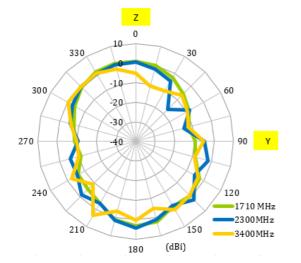


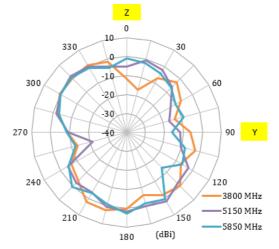




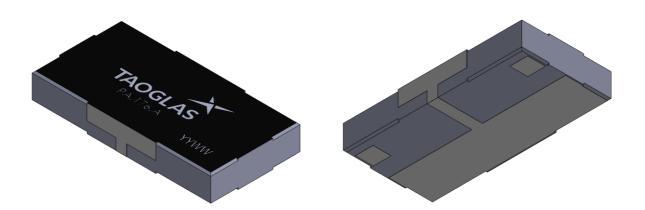


YZ Plane

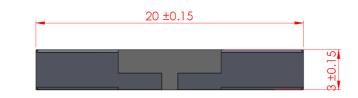


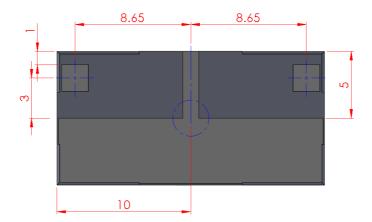














6. Antenna Integration Guide



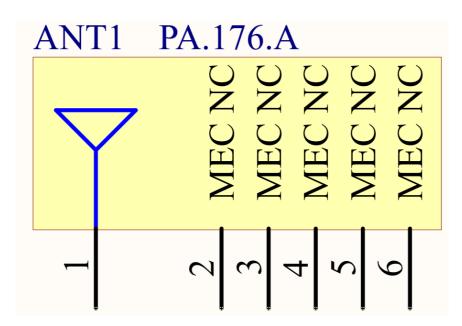




6.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 6 pins with only one pin (Pin 1) as functional. Pins 2, 3, 4, 5 and 6 are for mechanical strength.

Pin	Description
1	RF Feed
2, 3, 4, 5, 6	Mechanical, Not Connected



Please note you can download the design files, 3D model, 2D drawings and CST simulation files from the website here:

https://www.taoglas.com/product/5g-4g-wideband-cellular-smd-antenna/



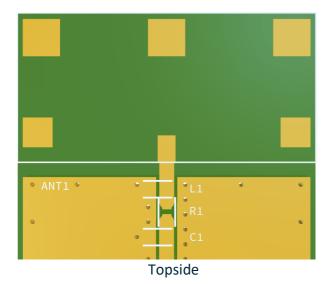
Antenna Integration

The antenna should ideally be placed on the PCB's shortest side to take advantage of the ground plane. Optimized matching components can be placed as shown.



6.3 PCB Layout

The footprint and clearance on the PCB must meet the antenna specification indicated below. An example of the PCB layout shows the antenna footprint with the recommended keep out area. Note the placement of the optimized components. The Pi-Matching network of L1 / R1 / C1 are placed within the ground plane. R1 and C1 are optional components but it is recommended to include these pads in case they are needed. For the evaluation board L1 is 5.6nH, R1 is 0 Ohm and C1 is Not Fitted. Please see Section 6.7 for further information. After the matching components the transmission line can be connected directly to the radio module.



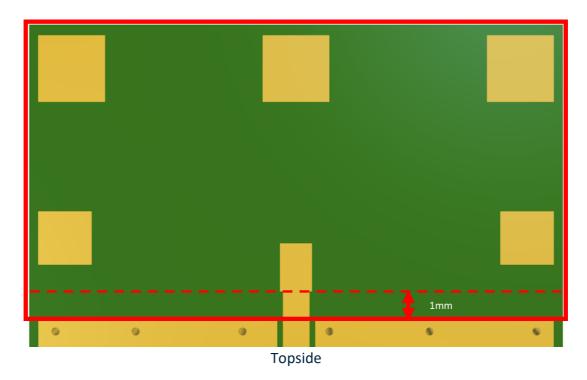


Bottom Side

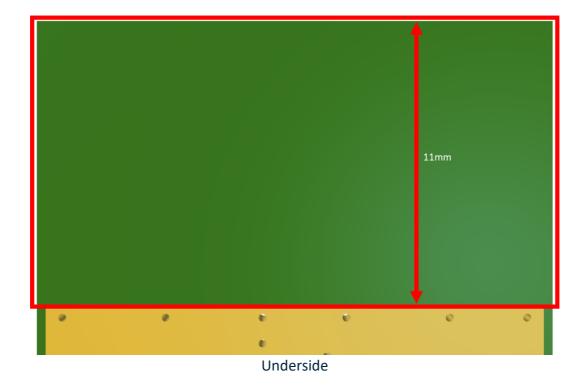


6.4 PCB Keep Out

Below shows the antenna footprint and clearance through ALL layers on the PCB. Only the antenna mechanical pads and connections to feed are present within this keep out area (marked RED). The keep out area extends to 1mm from the antenna feed pad to the ground area. This clearance area includes the bottom side and ALL internal layers on the PCB.

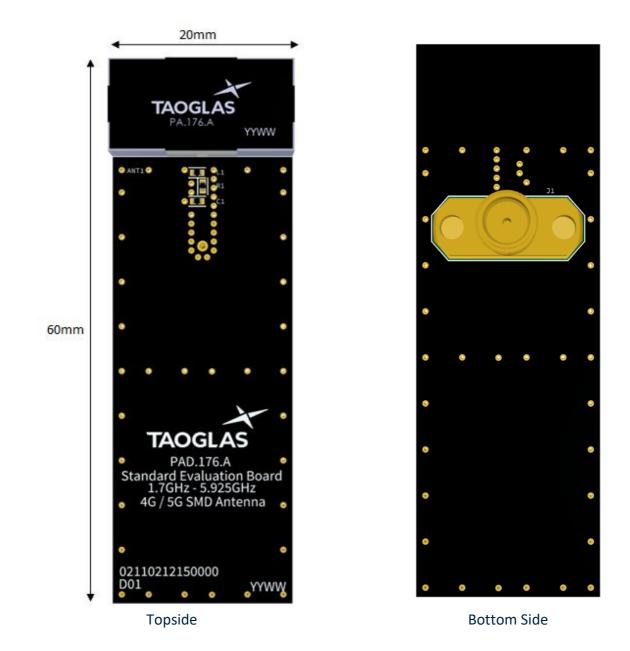


The image below, shows the underside of the PCB and the keep out area, indicated in RED. The keep out area extends to 11mm from the edge of the PCB covering the ground area. All layers must follow this clearance rule.





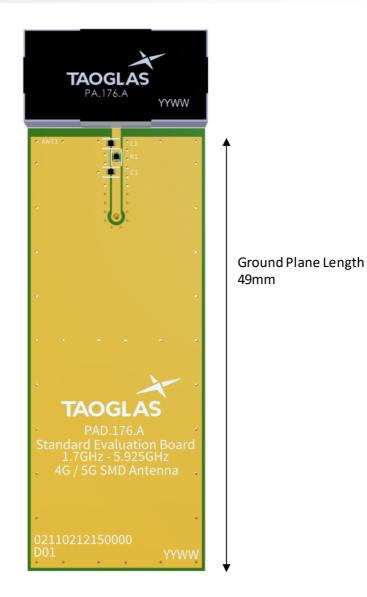




This evaluation board is a 2-layer stack-up. Please ensure a 50 Ohm transmission line is used in the design.



6.6 Evaluation Board Ground Plane Length

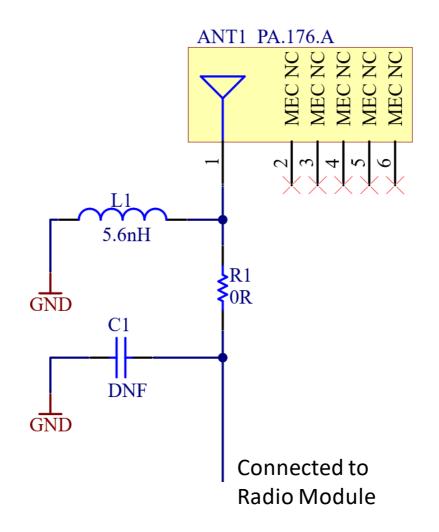


SPE-20-8-041-C



6.7 Evaluation Board Matching Circuit

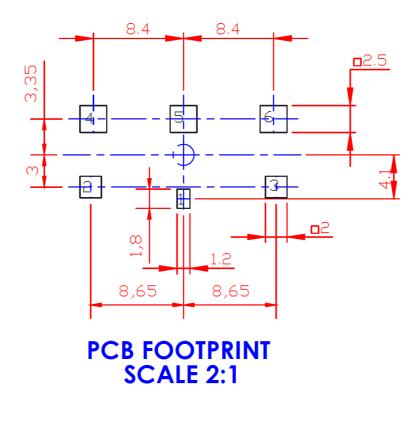
A matching component (L1) in parallel with the PA.176.A is required for the antenna to have optimal performance on the evaluation board, located inside the ground plane in the space specified in the above images. Additional matching components may be necessary for your device, so we recommend incorporating extra component footprints, forming a "pi" network, between the radio module and the edge of the ground plane.



Designator	Туре	Value	Description
L1	Inductor	5.6nH	Murata LQG15HS series
R1	Resistor	0 Ohms	Yageo RC0402 series
C1	capacitor	Not Fitted	



PCB Footprint Information



PIN:	DESCRIPTION:
1	Feed (50 ohm)
2,3,4,5,6	NC

Notes:

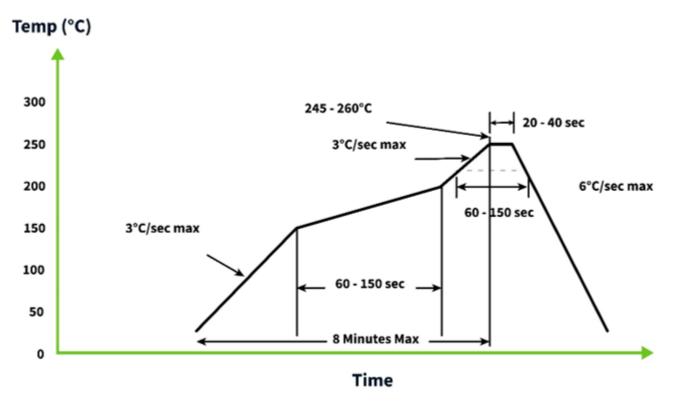
- 1. Pad 1 is connected to 50 ohm transmission line.
- 2. Pads 4,5 and 6 are the same size.
- 3. Pads 2 and 3 are the same size.
- 4. For PCB solder mark, allow for an area 0.1mm larger than the pads shown.
- 5. For PCB paste, allow for 90% coverage of the pad sizes shown.



Solder Reflow Profile

7.

The PA.176.A can be assembled by following the recommended soldering temperatures are as follows:



*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the PA.176.A when placing larger components on the board during subsequent reflows.

Note: Soldering flux classified ROL0 under IPC J-STD-004 is recommended.



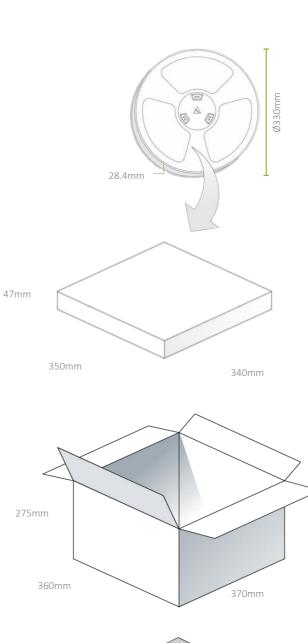
8. Packaging

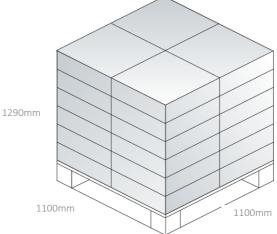
1000pcs PA.176.A per Tape & Reel Dimensions - Ø330*28.4 Weight - 1Kg

1000pcs PA.176.A per carton Dimensions - 350*340*47mm Weight - 1.2Kg

6000pcs PA.176.A per carton Dimensions - 360*370*275mm Weight - 6.8Kg

Pallet Dimensions: 1100*1100*1300mm 36 Cartons Per Pallet 9 Cartons Per Layer, 4 Layers







Changelog for the datasheet

SPE-20-8-041 - PA.176.A

Revision: C (Current Version)		
Date:	2023-10-25	
Changes:	Added Solder Reflow Profile	
Changes Made by:	Cesar Sousa	

Revision: B		
Date:	2020-11-05	
Changes:	Specifications table amended	
Changes Made by:	Dan Cantwell	

Revision: A (Original First Release)		
Date:	2020-06-12	
Notes:	Initial Release	
Author:	Jack Conroy	



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